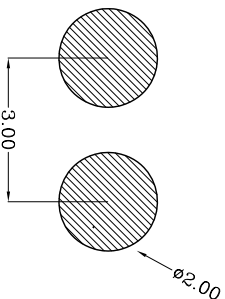
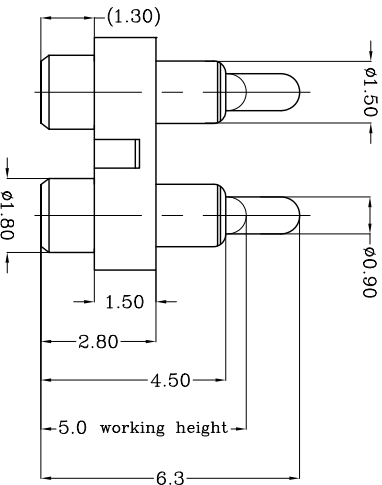
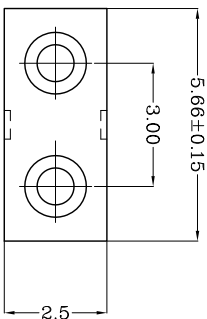
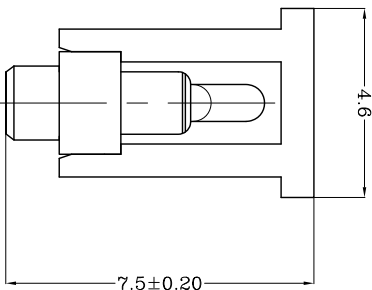
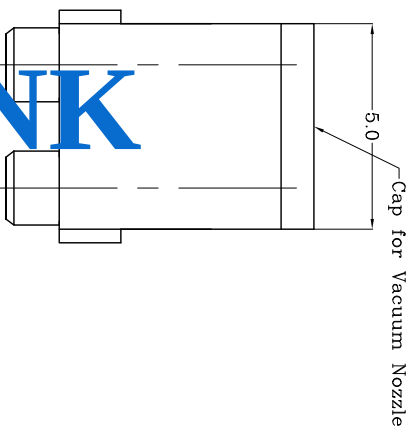
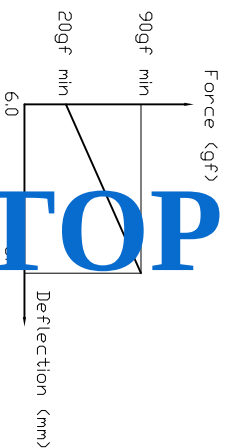


DWG NO.
C-100160



Recommended solder paste thickness is 0.10 mm
Recommended PCB Layout



USED ON

Notes:
1 Material, Housing: PA 4.6 (30% Glass Filled)

2 Mechanical demands:
Plating Plunger: Min 0.4um Au over 1.4um Ni
Plating Body: Min 0.10um Au over 1.4um Ni.

LDC		NAME		BATTERY POGO CONNECTOR 2 POSITIONS	
-		SURF. TEXTURE: 32/ V		PGC-1.5-6.3-R-2P-3.0PH	
DIST		REMOVE BURRS, BREAK SHARP EDGES R0.05 MAX DO NOT SCALE PRINT			
-		SCALE 1:1		SHEET 1 OF 1	
		A4		REV C	
		DWG NO. C-100160			
		L TR			
		REVISION			
		RECORD			
		APVD			
		DATE		2007/09/24	
		Update Remark			

DIMENSIONS IN MM TOLERANCES UNLESS OTHER SPECIFIED	MATL	HT TR	FIN
0 = ±		—	
0.0 = ±0.15		APVD	
0.00 = ±0.10		QIN	
0.000 = ±		REL	
0.000 = ±		CHK	
	<i>Top-Link Electronics</i>		<i>Top-Link Electronics Ltd.</i>

100160-2
PART NUMBER